



P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

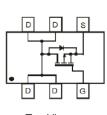
BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
001/	75mΩ @ V _{GS} = -10V	-3.3A
-30V	105mΩ @ V _{GS} = -4.5V	-2.8A

Description

This new generation MOSFET is designed to minimize the on-state resistance $(R_{DS(ON)})$ yet maintain superior switching performance, which makes it ideal for high-efficiency power management applications.

Applications

- General Purpose Interfacing Switch
- Power Management Functions



Top View Pin-Out



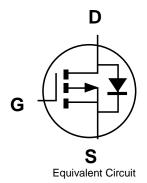
Top View

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish—Tin Finish Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (§3)
- Weight: 0.013 grams (Approximate)



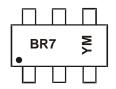
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP3068LVT-7	TSOT26	3000/Tape & Reel
DMP3068LVT-13	TSOT26	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



BR7 = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

Year	2018	2019	20	020	2021	2022	2	2023	2024	20:	25	2026
Code	F	G		Н		J		K	L	N	1	N
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-30	V	
Gate-Source Voltage	V _{GSS}	±12	V	
Continuous Drain Current (Note 6) V _{GS} = -4.5V	I _D	-2.8 -2.2	А	
Maximum Body Diode Forward Current (Note 6)		Is	-1.6	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 19	6)	I _{DM}	-20	Α

Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		P_{D}	1.25	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\Theta JA}$	100	°C/W
Total Power Dissipation (Note 6)		P _D	1.8	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R _{OJA}	70	°C/W
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

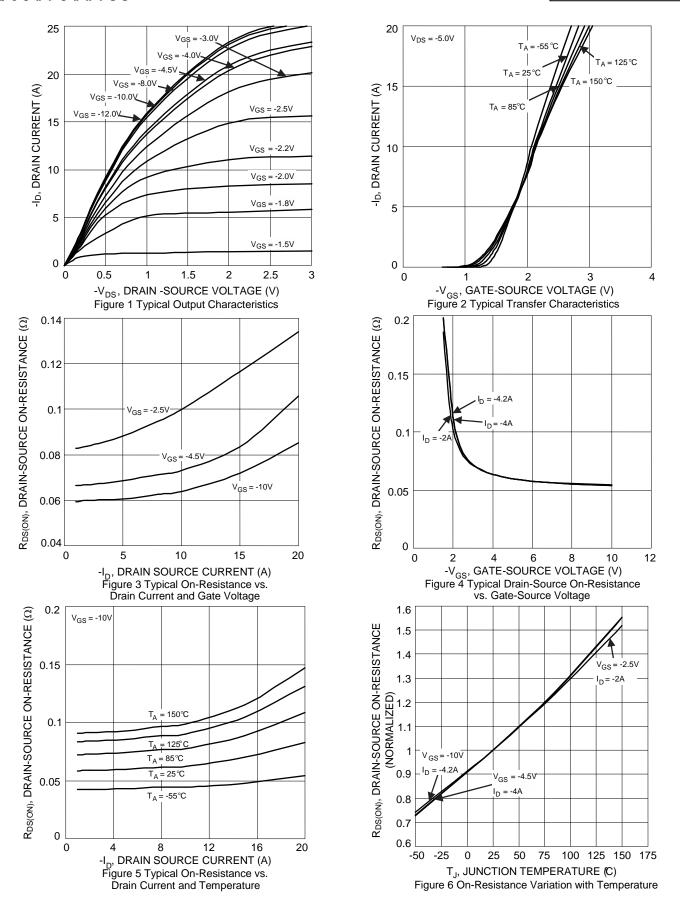
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-30	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	-1.0	μA	$V_{DS} = -30V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	-0.5	_	-1.3	V	$V_{DS} = V_{GS}, I_{D} = -250\mu A$	
				75		$V_{GS} = -10V, I_D = -4.2A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	_	105	mΩ	$V_{GS} = -4.5V$, $I_{D} = -4.0A$	
	20(0.1)		_	150		$V_{GS} = -2.5V, I_D = -2.0A$	
Diode Forward Voltage	V_{SD}	_	_	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	708	_	pF	V 45V V 6V	
Output Capacitance	Coss	_	57		рF	$V_{DS} = -15V, V_{GS} = 0V$ - f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	47	_	рF	1 – 1.000112	
Gate Resistance	R _G	_	14		Ω	$V_{GS} = 0V, V_{DS} = 0V, f = 1.0MHz$	
Total Gate Charge	Q_{g}	_	7.3	_	nC		
Gate-Source Charge	Q_{gs}	_	1.2	_	nC	$V_{GS} = -4.5V, V_{DS} = -15V, I_{D} = -4A$	
Gate-Drain Charge	Q_{gd}	_	1.7	_	nC		
Turn-On Delay Time	t _{D(ON)}	_	3.5	_	ns		
Turn-On Rise Time	t _R	_	15.8	_	ns	$V_{DS} = -15V, V_{GS} = -10V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	70.3	_	ns	$R_G = 6.0\Omega, I_D = -4A$	
Turn-Off Fall Time	t _F	_	33.9	_	ns		

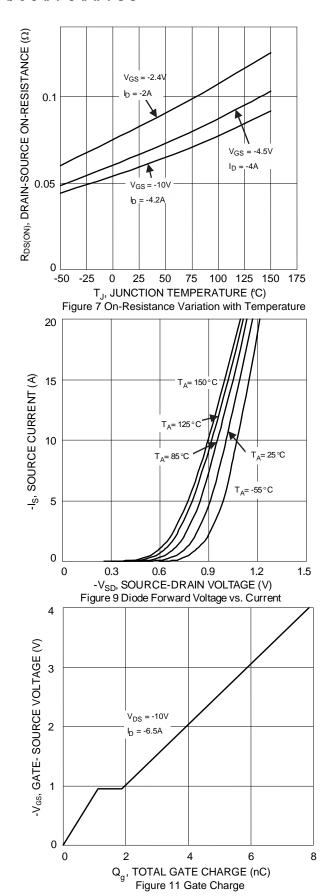
Notes:

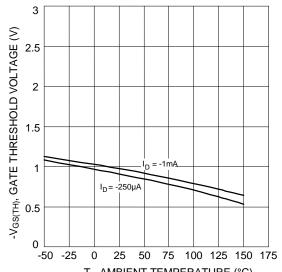
- Device mounted on FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.



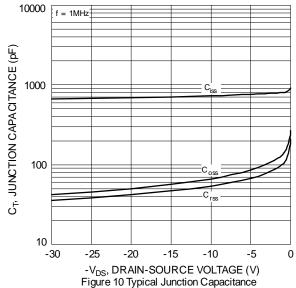








 $\rm T_{\!A}, \, AMBIENT \, TEMPERATURE \, (^{\circ}C)$ Figure 8 Gate Threshold Variation vs. Ambient Temperature



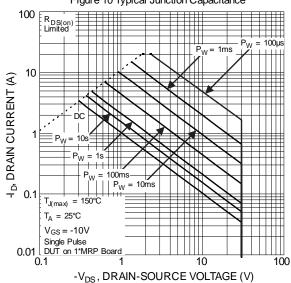
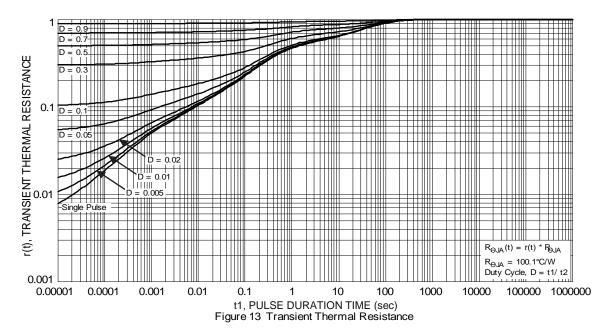


Figure 12 SOA, Safe Operation Area

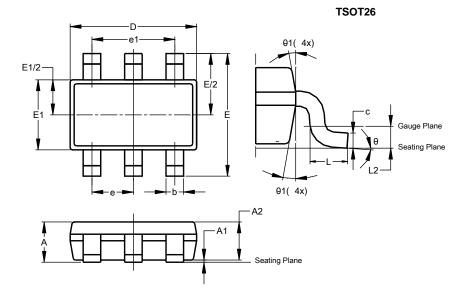






Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

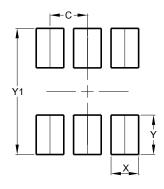


	TSOT26							
Dim	Min	Max	Тур					
Α		1.00	-					
A1	0.010	0.100	_					
A2	0.840	0.900	_					
D	2.800	3.000	2.900					
Е	2.800 BSC							
E1	1.500	1.700	1.600					
b	0.300	0.450	-					
С	0.120	0.200	_					
е	e 0.950 BSC							
e1	1.900 BSC							
L	0.30 0.50 —							
L2	0.250 BSC							
θ	0°	8°	4°					
θ1	4°	12°	_					
Α	All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT26



Dimensions	Value (in mm)
C	0.950
Х	0.700
Y	1.000
Y1	3.199



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